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Receipt

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Atty. Dkt.: 10517/102

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANTS: Koichi HIRAMATSU et al.  
SERIAL NO. : 09/880,925  
FILED : JUNE 15, 2001  
FOR : MOLDING CLAMPING APPARATUS AND MOLD  
CLAMPING METHOD  
ART UNIT : 1722

ASSISTANT COMMISSIONER  
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Washington, DC 20231

**REQUEST FOR ISSUANCE OF A CORRECTED FILING RECEIPT**

SIR:

Enclosed is a copy of the official filing receipt which indicates the correction of the priority documents that need to be corrected as follows:

Replace "JAPAN 2001-156393 03/28/2001"  
With -- JAPAN 2001-156393 05/25/01--

Please add omitted priority document: JAPAN 2001-092764 03/28/2001

Issuance of a corrected filing receipt is respectfully requested.

Respectfully submitted,

Dated: August 29, 2001

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/880,925	06/15/2001	1722	908	10517/102	27	31	3

CONFIRMATION NO. 5667

23838

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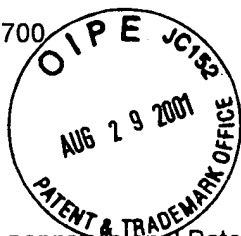
WASHINGTON, DC 20005

## FILING RECEIPT



\*OC00000006421362\*

Date Mailed: 08/14/2001



Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

## Domestic Priority data as claimed by applicant

## Foreign Applications

JAPAN 2000-181314 06/16/2000

JAPAN 2001-156393 03/28/2001 replace with --05/25/01--

JAPAN 2001-156394 05/25/2001

add omitted priority document JAPAN 2001-092764 03/28/2001

If Required, Foreign Filing License Granted 08/13/2001

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

## Title

Mold clamping apparatus and mold clamping method

## Preliminary Class

425

